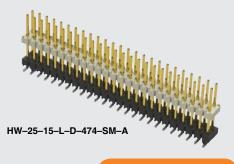




HW-15-08-G-S-335-SM





(2.54 mm) .100"

HW-SM SERIES

<u>FLEXIBLE .025" SQ BOARD STACKERS</u>

Board Mates:

SSW, SSQ, ESW, ESQ, CES, SLW, BSW, BCS, SSM, HLE, PHF

Cable Mates:

IDSS, IDSD, SMSD, SMSS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HW-SM

Insulator Material:

Top: Natural LCP
Bottom: Black LCP
Terminal Material:
Phosphor Bronze
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Operating Temp Range:
-55 °C to +125 °C with Gold
-55 °C to +105 °C with Tin
RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity:

(0.15 mm) .006" max*
*(.004" stencil solution
may be available; contact
IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- · Other platings
- Locking Clip (Manual placement required) available with double row –SM

Contact Samtec.

Notes:

For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact jpg@samtec.com for more information.

This Series is non-standard, non-returnable.



02 thru 36

(7.37) .290 PLATING OPTION

ING ROW OPTION

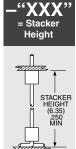
STACKER HEIGHT





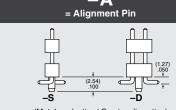






-"XXX" = Polarized

Specify omitted pin position

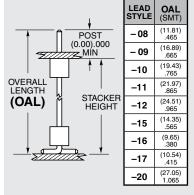


(Metal or plastic at Samtec discretion)

TR– Reel Pa

= Tape & Reel Packaging (4–27 pins per row only) (Not Available on Lead Styles 10, 11, 12 & 20)

Specify LEAD STYLE from chart



– F = Gold flash on contact, Matte Tin on tail

—L

= 10 $\mu^{\text{\tiny{II}}}$ (0.25 $\mu\text{m})$ Gold on contact area of longer tail, Matte Tin on tail

-G

= 10 μ " (0.25 μ m) Gold on contact area of longer tail, Gold flash on balance

-T

Due to technical progress, all designs, specifications and components are subject to change without notice.